



Part Name	TFT Display Module TFT
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SWI Part ID SWI	LH420NB-F07
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Customer Part ID	
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Manufactured By	Shineworld Innovations Limited
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PRODUCT SPECIFICATION

Version: 1.0

Approved By	Prepared By	Customer Approval
Yang D 	Luis Liu	

The information in this document is subject to change without notice.

Please ask sales personnel from Shineworld Innovations Limited for updated specifications before product design and release of the orders.

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REVISION RECORD

DATE	CONTENTS	REVISION	PREPARED BY
2022-12-03	First Release	V1.0	Luis Liu

1) GENERAL DATA

NO.	ITEM	SPECIFICATIONS	UNIT
1	Display Mode	Mono TFT	-
2	Diagonal Size	4.2	Inch
3	Resolution	300 x 400	Dots
4	Active Area	63.6(H) x 84.8(V)	mm
5	Outline Dimension	67.6(H) x 91.0(V)	mm
6	Thickness	1.1 ±0.1	mm
7	Pixel Pitch	0.212(W) x 0.212(H)	mm
8	Pixel Size	0.212(W) x 0.212(H)	mm
9	Display Driver IC IC	ST7306	-
10	Touch Driver IC IC	No Touch	-
11	Display Color	White	-
12	Gray Scale	1	Bit
14	Contrast Ratio	15:1 (Typ.)	-
15	Interface	4-wire SPI	-
16	IC Package Type IC	COG	-
17	Module Connecting Type	Connector	-
18	Weight	14±10%	g
19	Pins	24	Pins
20	Operating Temperature	-20~70	
21	Storage Temperature	-30~80	

2) ABSOLUTE MAXIMUM RATINGS

Unless otherwise specified, VSS = 0V

VSS=0V

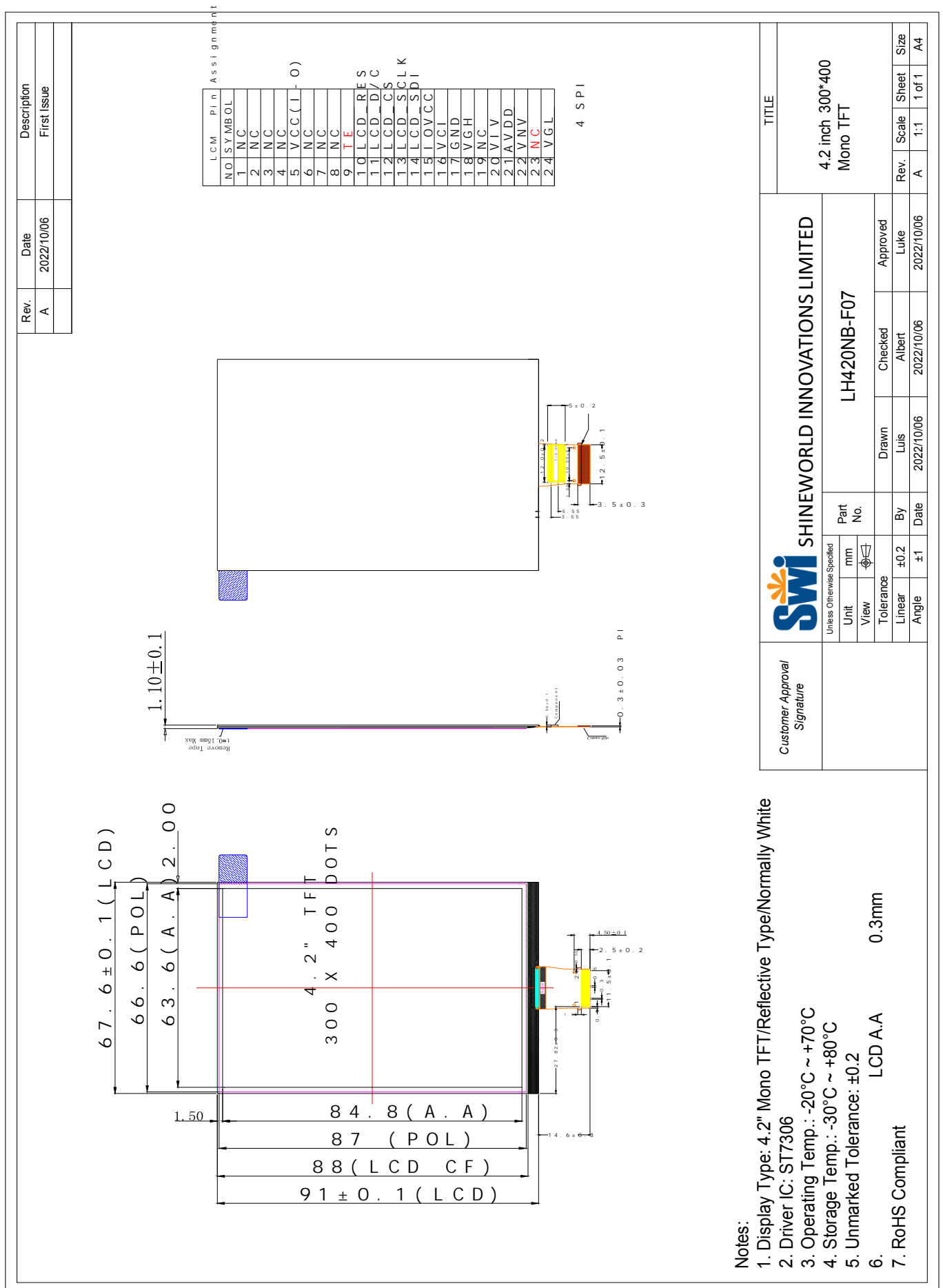
Items	Min.	Max.	Unit	Remark
I/O Supply Voltage (VDD) I/O (VDD)	-0.3	+4.0	V	
Analog Supply Voltage (IOVCC) (IOVCC)	-0.3	+4.0	V	
Logic Input Voltage (VIN) (VIN)	-0.3	IOVCC+0.5	V	
Operating Temperature (T _{OP}) T _{OP}	-20	70		
Storage Temperature (T _{ST}) T _{ST}	-30	80		

NOTE:

Absolute Maximum Ratings means the product can withstand short-term, NOT more than 120 hours. If the product is a long time to withstand these conditions, the life time would be shorter.

120

3) EXTERNAL DIMENSIONS



4) ELECTRICAL CHARACTERISTICS

4.1. DC Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Supply Voltage	VDD	2.55	2.8	3.3	V	
Interface Operation Voltage	IOVCC	1.65	1.8	3.3	V	
Gate Driver High Voltage	VGH	8	-	16.5	V	
Gate Driver Low Voltage	VGL	-10	-	-5	V	
Input voltage 'H' level	VIH	$0.7 \times \text{IOVCC}$	-	IOVCC	V	
Input voltage 'L' level	VIL	VSS	-	$0.3 \times \text{IOVCC}$	V	
Output voltage 'H' level	VOH	$0.8 \times \text{IOVCC}$	-	IOVCC	V	
Output voltage 'L' level	VOL	VSS	-	$0.2 \times \text{IOVCC}$	V	

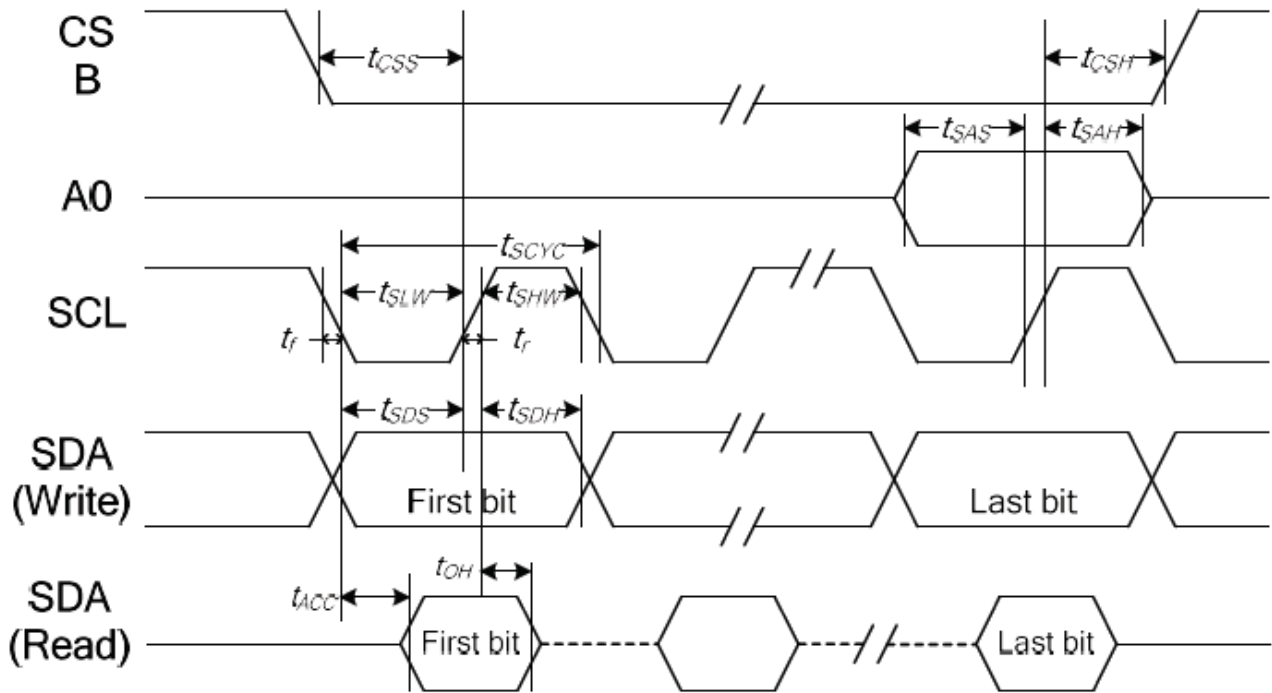
4.2. Current Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Operating Current for VDD VDD	IDD	-	30	-	uA	Power consumption lasts 1.8s, average 1.8s

Note: Operating Current for VDD Test Report VDD

4.3. AC Characteristics

4.3.1. Serial interface Characteristics(4-line serial): 4



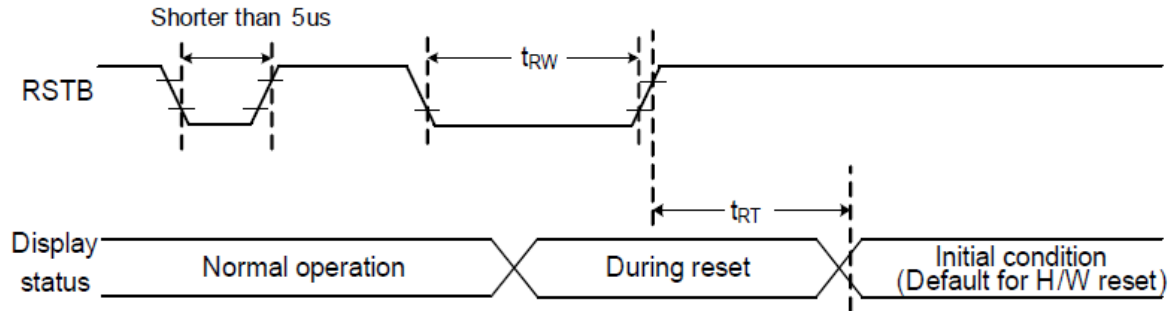
VDDI = 1.8~3.3V, Ta = 25°C

Item	Signal	Symbol	Condition	Min.	Max.	Unit
Serial clock period (Write)	SCL	t_{SCYC}		30	—	ns
Serial clock period (Read)				150	—	
SCLK "H" pulse width (Write)		t_{SHW}		15	—	
SCLK "H" pulse width (Read)				60	—	
SCLK "L" pulse width (Write)		t_{SLW}		15	—	
SCLK "L" pulse width (Read)				60	—	
Address setup time	A0	t_{SAS}		10	—	
Address hold time		t_{SAH}		10	—	
Data setup time	SDA (Write)	t_{SDS}		10	—	
Data hold time		t_{SDH}		10	—	
Read data access time	SDA (Read)	t_{ACC}	For maximum CL=30p	10	50	
Read data output disable time		t_{OH}	For minimum CL=8p	15	50	
CSB-SCLK time	CSB	t_{CSS}		10	—	
CSB-SCLK time		t_{CSH}		10	—	

Note:

- The input signal rise and fall time (t_r , t_f) are specified at 15 ns or less.
- (t_r , t_f) 15 ns
- All timing is specified using 20% and 80% of VDDI as the standard.
- 20% 80% VDDI

4.3.2. Reset Timing:



VDDI = 1.8~3.3V, Ta = 25°C

Item	Symbol	Condition	Min.	Max.	Unit
Reset "L" pulse width	tRW		1	—	ms
Reset cancel	tRT	Note1, 5 (sleep-in mode)	—	5	ms
		Note1, 6, 7 (sleep-out mode)	—	120	ms

Notes:

1. The reset cancel includes also required time for loading ID bytes, VSource setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

1. ID VSource NVM RESX 5
HW tRT

2. Spike due to an electrostatic discharge on RSTB line does not cause irregular system reset according to the table below

2. RSTB

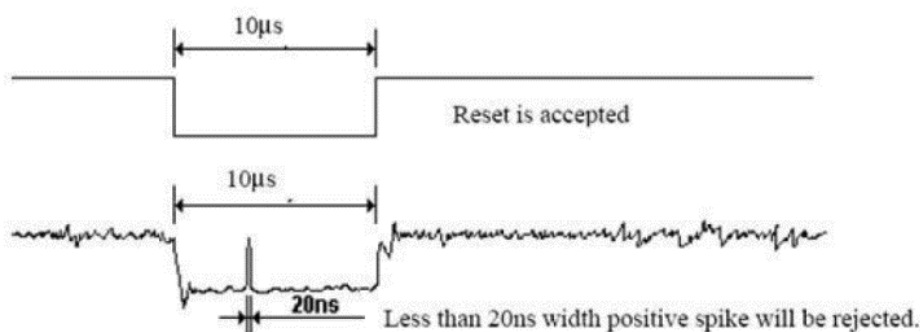
RSTB Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence which maximum time is 120 ms, when Reset Starts at Sleep Out-mode. The display remains the blank state in Sleep In-mode). Then return to Default condition for Hardware Reset

3. 120 Reset Sleep-Out Sleep-In

4. Spike Rejection also applies during a valid reset pulse as shown below

4.



5. When Reset applied during Sleep-In Mode.

6. When Reset applied during Sleep-Out Mode.

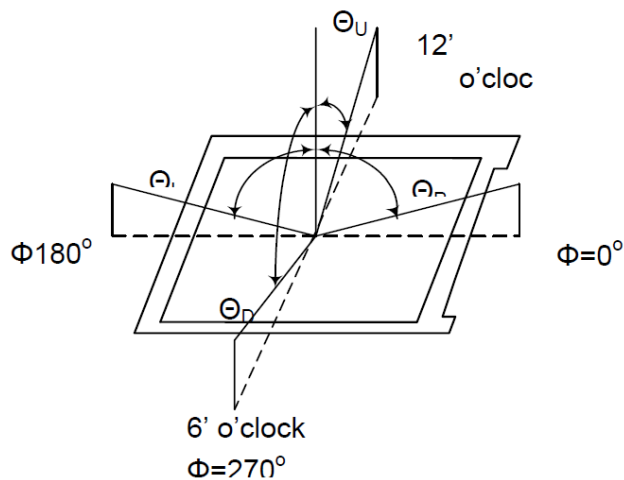
7. It is necessary to wait 10ms after releasing RSTB before sending commands. Also Sleep Out command cannot be sent for 120 ms.

7. RSTB 10 120 Sleep Out

5) ELECTRO-OPTICAL CHARACTERISTICS

Items	Symbol	Condition		Min.	Typ.	Max.	Unit	Note
Viewing angle		=0		-	65	-	Deg	Note1
		=180		-	65	-		
		=90		-	65	-		
		=270		-	65	-		
Reflectance	T%	-	-	-	20	-	%	
Contrast Ratio	CR	-		-	15	-	-	Note2
Response Time	Tr+Tf	=0 =0		-	30	40	ms	Note3

Note1. Definition of Viewing Angle :

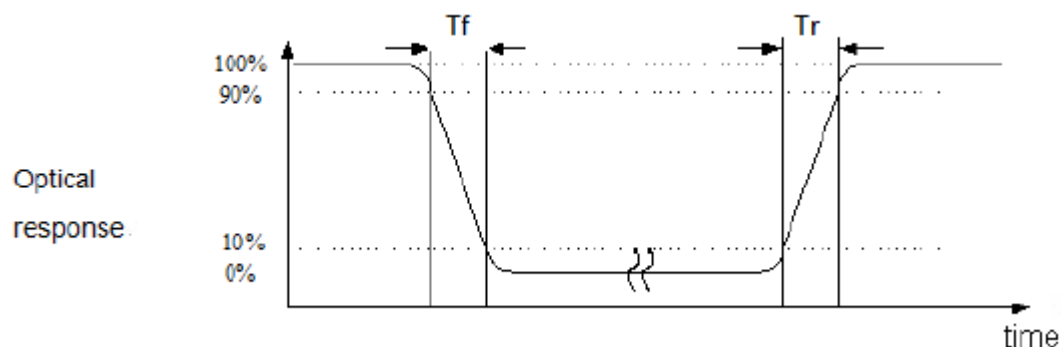


Note 2. Definition of Contrast Ratio

$$\text{Contrast Ratio} = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

Note3. Definition of Response Time : Sum of Tr and Tf :

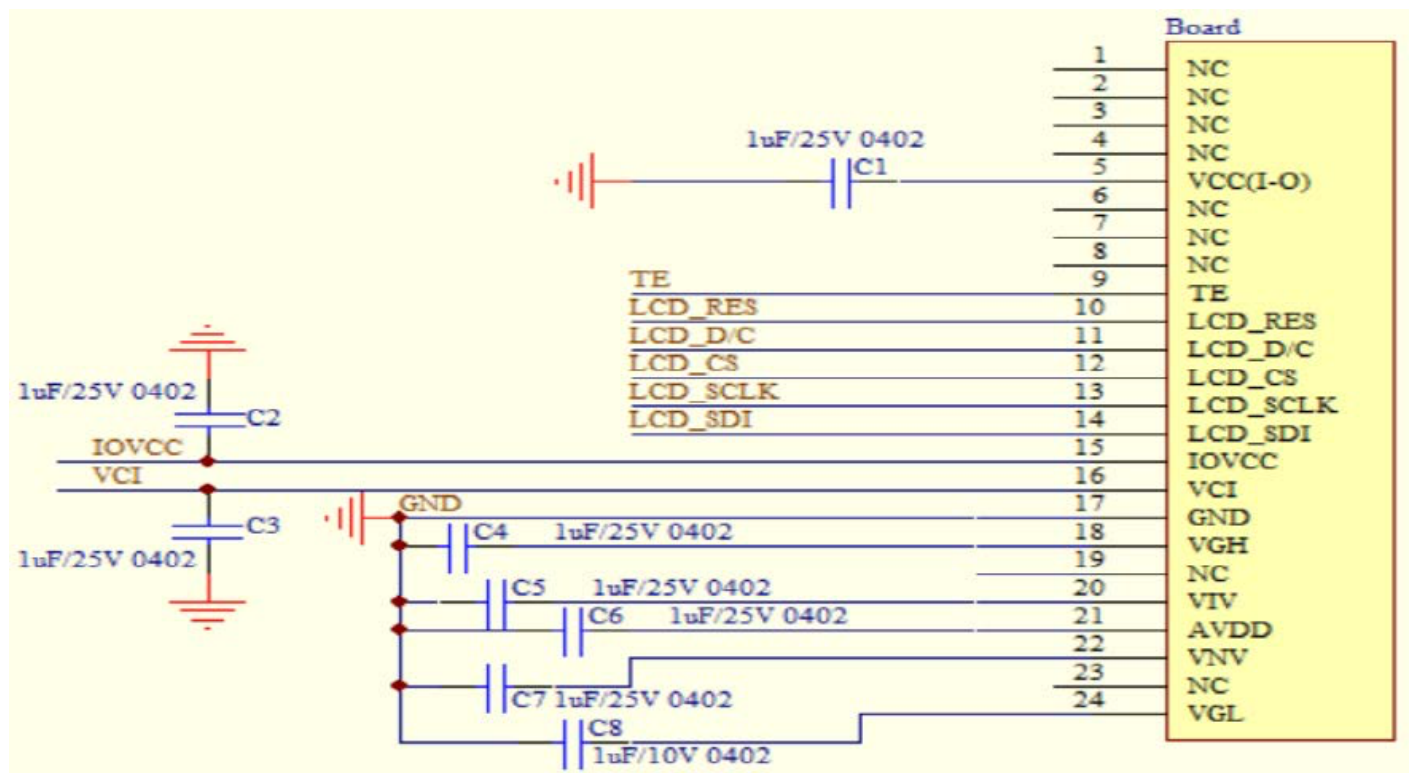
Tr Tf



6) INTERFACE PIN CONNECTIONS

No.	Symbol	Description
1~4	NC	NC
5	VCC(I-O)	VCCI is the power source of digital circuits
6~8	NC	NC
9	TE	Tearing effect signal is used to synchronize MCU to frame memory Writing
10	LCD_RES	Reset input pin. internal initialization procedure is executed
11	LCD_D/C	Display data/command selection pin in 4-line serial interface. /
12	LCD_CS	Chip selection pin; Low enable, high disable.
13	LCD_SCLK	This pin is used to be serial interface clock
14	LCD_SDI	SPI interface input/output pin. the data is latched on the rising edge of the SCL signal. SPI /
15	IOVCC	Power Supply(Digital). IOVCC=1.65V-3.3V
16	VCI	Power Supply(Analog). VCI=2.55V-3.3V
17	GND	Ground
18	VGH	Power output(Positive) pin for gate driver
19	NC	NC
20	VIV	Power output pin for analog driver
21	AVDD	Power output pin for analog driver
22	VNV	Power output pin for analog driver
23	NC	NC
24	VGL	Power output(Negative) pin for gate driver

7) SCHEMATIC EXAMPLE



8) RELIABILITY TEST

No.	Item	Conditions	Inspection after Test
1	High Temperature Storage	80 120 hours	Inspection after 2~4 hours storage at room temperature, the sample shall be free from defects: , LCD 2~4 1. Air Bubble in the LCD; 2. Non-display; 4. Missing Segments; 5. Glass Crack; 6. Current Idd is Twice Higher than Initial Value Idd 2
2	Low Temperature Storage	-30 120 hours	
3	High Temperature Operating	70 120 hours	
4	Low Temperature Operating	-20 120 hours	
5	High Temperature & High Humidity Storage	+60 ,90% RH, 120 hours	
6	Thermal Shock	-10 ~ 60 (30min) (30min) Change time:5min 10CYC	
7	ESD Test	C=150pF, R=330,5points/panel Air:±4KV, 5times; Contact:±2KV, 5 times; 30%~60%).	
8	Vibration (Non-operation)	Frequency: 10 ~ 55Hz Amplitude: 1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z. (6 hours for total) (Package condition).	
9	Box Drop Test	1 Corner 3 Edges 6 faces,76 (MEDIUM BOX)	

Remark:

- The test samples should be applied to only one test item.
- Sample size for each test item is 5~10pcs.
5 10 .
- For Damp Proof Test, Pure water(Resistance
10M
- In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.
- Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic
- The color fading mura of polarizing filter should not care.
Mura

9) OUTGOING QUALITY CONTROL SPECIFICATIONS

9.1. Standard

According to GB/T2828.1-2003/ISO 2859-1:1999 and ANSI/ASQC Z1.4-1993, General Inspection Level II.

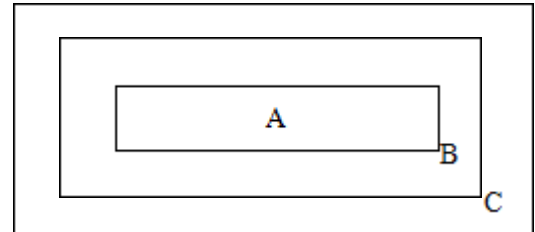
9.2. Definition

- 1) Major Defect: The defect that greatly affect the usability of product.
- 2) Minor Defect: The other defects, such as cosmetic defects, etc.
- 3) Definition of Inspection Zone :

Zone A: Active Area

Zone B: Viewing Area except Zone A Zone

C: Outside Viewing Area



Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of quality and assembly to customer's product.

A B A C
C

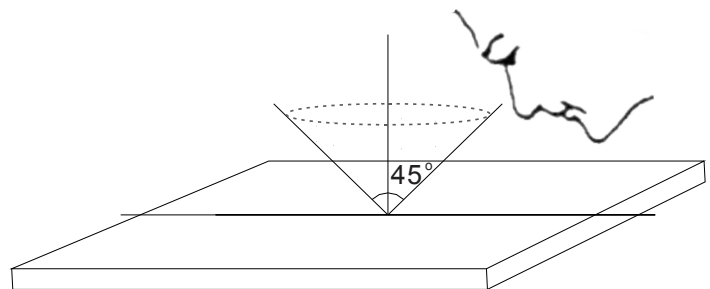
9.3. Inspection Methods

- 1) General Inspection: under 20W x 2 or 40W fluorescent light, about 30cm viewing distance, within 45° viewing angle, under

±

20W x 2 40W
45° ±

30cm



- 2) The Brightness and Color Coordinate Inspection: By CS2000/09A-LCD-117 or the equal equipment, in

±

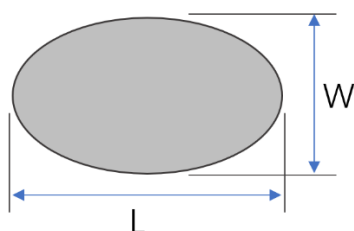
CS2000/09A-LCD-117

±

9.4. Inspection Criteria

- 1)Z Definition of the Defect Size :

Spot Shape :



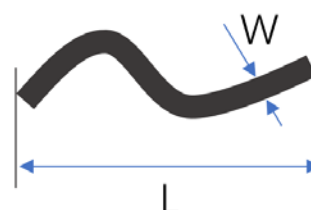
$$= (L+W)/2$$

L: Length

W: Width

N: Number

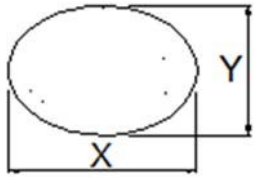
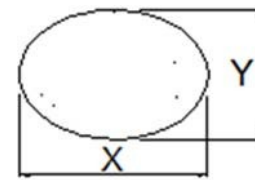
Line Shape :

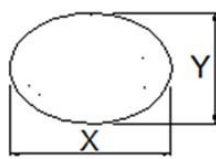


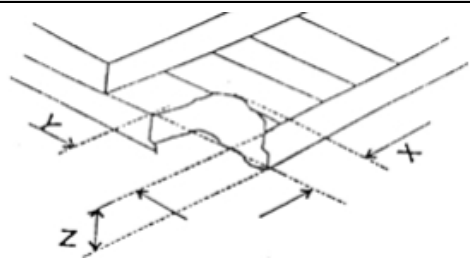
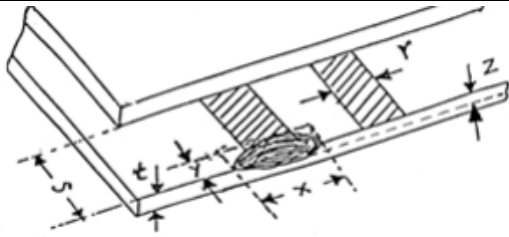
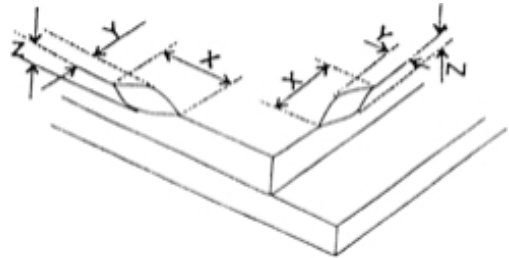
2) Major Defect: AQL= 0.65

Item	Criterion
Function Defect	1. No display or abnormal display is not accepted
	2. Open or short is not accepted.
	3. Bright/Dark line or other line shapes are not accepted /
	4. Missing vertical or horizontal segment are not accepted
	5. Back Light has no lighting, flickering or abnormal lighting are not accepted
Component Defect	Missing/Broken component is not accepted. /
Outline Dimension	Outline dimension exceeding the spec is not accepted.
Glass Crack	Glass crack tends to enlarge is not accepted.
FPC Defect	Split/Broken FPC is not accepted. FPC

3) Minor Defect: AQL= 1.5

Item	Criterion				
Clear Spot Defect (Black & White Spot, Foreign Particle, Pinhole, Stain under Polarizer) (, Pin)	Size (mm)		Accepted Qty.		
			Area A + Area B	Area C	
		0.1		Ignored	
		0.10	0.15	N 2	Ignored
		0.15	0.20	N 1	
		0.20		N=0	
	Note: = (x + y) / 2				
Dim Spot Defect (Circle Shaped and Dim Edged Defects) ()	Size (mm)		Accepted Qty.		
			Area A + Area B	Area C	
		0.2		Ignored	
		0.20	0.40	N 2	Ignored
		0.40	0.60	N 1	
		0.60		N=0	
	Note: = (x + y) / 2				
Dot (Pixel) Defect	Item		Area A + Area B	Area C	
	Bright Dot		N=0	Ignored	
	Dark Dot		N 4		

Item	Criterion			
Line Defect (Dimming and Lighting Line) ()	L (Length): mm	W (Width): mm	Area A + Area B	Area C
	/	W 0.02	Ignored	
	L 3.0	0.02 W 0.03	N 2	Ignored
	L 2.0	0.03 W 0.05	N 1	
	/	0.05 W	As spot defect	
Note: The total of spot defects and line defects shall not exceed 4 PCS. The distance between two lines defects must exceed 1 mm				
Mura	Judged OK if unviewable by using 3% ND Filter on 128 gray scale pattern. 128 3%ND OK			
FPC Defect	Crack, deep fold and deep pressure mark on the FPC are not accepted			
Polarizer Stain	Stain which can be wiped off lightly with a soft cloth or similar cleaning is accepted, otherwise, according to the Spot Defect and the Line Defect.			
Polarizer Scratch	1. If scratch can be seen during operation, according to the criterions of the Spot Defect and the Line Defect.			
	2. If scratch can be seen only under non-operation or some special angle, the criterion is as below:			
	L (Length): mm	W (Width) : mm	Area A + Area B	Area C
	/	W 0.03	Ignore	
	L 10.0	0.03 W 0.05	N 2	Ignore
	L 5.0	0.05 W 0.08	N 1	
	/	0.08 W	N=0	
Polarizer Air Bubble	Size (mm)		Area A + Area B	Area C
		0.20	Ignored	
		0.20 0.30	N 2	Ignored
		0.30 0.50	N 1	
		0.50	N=0	
	Note: $= (x + y) / 2$			

Item	Criterion						
Glass Defect (Glass Chipped) ()	1. On the corner (mm) (mm) <table><tr><td>x</td><td>y</td><td>z</td></tr><tr><td>2.0</td><td>s</td><td>Disregard</td></tr></table> 	x	y	z	2.0	s	Disregard
	x	y	z				
	2.0	s	Disregard				
	2. On the Bonding Edge (mm) (mm) <table><tr><td>x</td><td>y</td><td>z</td></tr><tr><td>a/4</td><td>s/3 & 0.7</td><td>Disregard</td></tr></table> 	x	y	z	a/4	s/3 & 0.7	Disregard
x	y	z					
a/4	s/3 & 0.7	Disregard					
3. On the Other Edges (mm) (mm) <table><tr><td>x</td><td>y</td><td>z</td></tr><tr><td>3.0</td><td>0.5</td><td>Disregard</td></tr></table> 	x	y	z	3.0	0.5	Disregard	
x	y	z					
3.0	0.5	Disregard					
Note: t : Glass Thickness; s : Pad Width; a : Edge Length, x : Chip Length, y : Chip Width, z : Chip Thickness t : ; s : Pad ; a : ; x : ; y : ; z :							

4) Parts Defect

Item	Criterion
Parts Alignment	Minor Defect: IC and FPC/heat-seal lead width is more than 50% beyond lead pattern. Chip or solder component shifted from center more than 50% of the pad outline. IC/FPC 50%. 50% / .
SMT	According to the <Acceptability of Electronic Assemblies> IPC-A-610E Class 2 Standard, component missing or function defect is Major defect, the others are Minor defect. IPC-A-610E < > 2

10) CAUTIONS FOR USING LCD MODULES

10.1. Precautions for Handling LCD Modules LCD

- 1) The display panel is made of glass and polarizer. As glass is fragile. It tends to become chipped during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact.
- 2) Do not apply excessive force to the display surface or the adjoining areas since this may cause abnormal. Do not touch the display with bare hands. This will stain the display area (some cosmetics are determined to the polarizer).
- 3) The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on it. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming in to contact with room temperature air.

LCD

HB

- 4) If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents.
 - Isopropyl alcohol
 - Ethyl alcoholDo not scrub hard to avoid damaging the display surface.

:

-
-

- 5) Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.

- Water
- Ketone
- Aromatic solvents

Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading. Avoid contact with oil and fats.

-
-
-

- 6) Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.
- 7) When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable.
LCD
- 8) Do not attempt to disassemble or process the LCD module.
LCD
- 9) NC terminal should be open. Do not connect anything.
- 10) If the logic circuit power is off, do not apply the input signals.
- 11) Electro-Static Discharge Control: Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

ESD : LCD CMOS CMOS

- Before removing LCD from its packing case or incorporating it into a set, be sure the module and your body have the same electric potential. Be sure to ground the body when handling the LCD modules.
LCD
- Tools required for assembling, such as soldering irons, must be properly grounded. Make certain the AC power source for the soldering iron does not leak. When using an electric screwdriver to attach LCM, the screwdriver should be of ground potentiality to minimize as much as possible any transmission of electromagnetic waves produced sparks coming from the commutator of the motor.
- To reduce the amount of static electricity generated, do not conduct assembling and other work under dry conditions. To reduce the generation of static electricity be careful that the air in the work is not too dry. A relative humidity of 50%-60% is recommended. As far as possible make the electric potential of your work clothes and that of the work bench the ground potential.

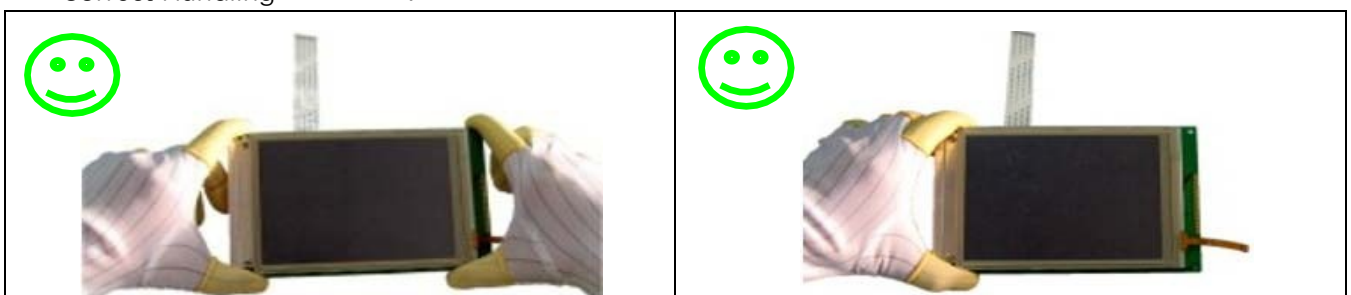
50%-60%

- The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.
LCD

- 12) LCD module is easy to be damaged. Please note below and be careful for handling.



LCD

- i. Correct Handling :



As showed above, please handle with anti-static gloves around LCD module edges.

ii. Incorrect Handling :

 <p>Don't touch IC directly IC</p>	 <p>Don't hold the surface of panel</p>	 <p>Don't stack LCD modules LCD</p>
 <p>Don't hold the surface of IC IC</p>	 <p>Don't operate with sharp stick such as pens</p>	 <p>Don't stretch interface of input, such as FPC</p>

10.2. Precautions for Storing LCD Module LCD

When storing the LCD modules, the following precautions are necessary:

LCD :

- 1) Store them in a sealed polyethylene bag with the desiccant.
- 2) Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature 0~35 60%RH.
40%RH 60%RH
- 3) The polarizer surface should not come in contact with any other objects (We advise you to store them in the anti-static electricity container in which they were shipped).
- 4) To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.
LCD
 - Exposed area of the printed circuit board.
 - Terminal electrode sections.

10.3. Precautions for Transportation

- 1) During shipment, please handle with care. The packaging bag can not be broken, step on trap. Packaging Carton layer height can not be over two meters.
2 .
- 2) The transportation process should pay attention to the waterproof and moisture-proof measures. Product can not be watering. Ethylene sealed bags can not be unsealed.

10.4. Using LCD Modules LCD

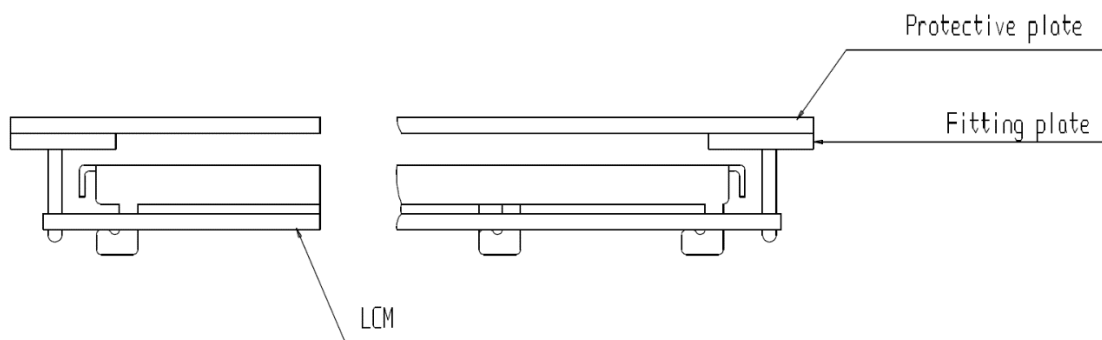
Installing LCD Modules LCD

- 1) When assembling the LCD module into other equipment, the spacer to the bit between the LCD module and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be $\pm 0.1\text{mm}$.

LCD

± 0.1

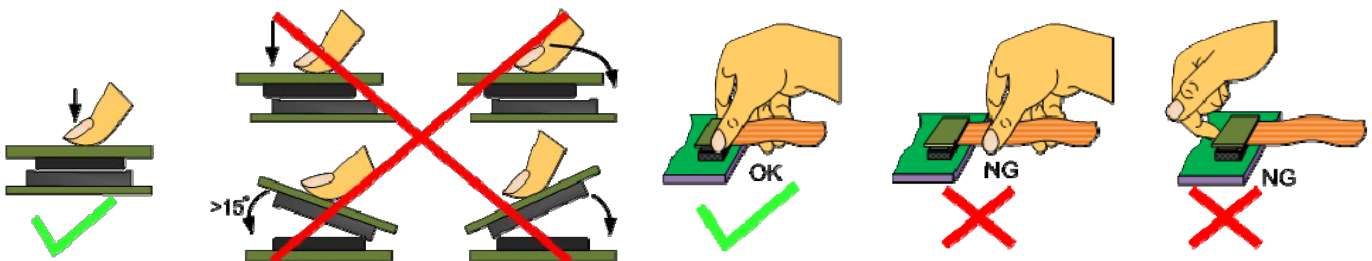
- 2) Cover the surface with a transparent protective plate to protect the polarizer and LC cell.



- 3) Precaution for assembling the module with BTB connector:

LCD

Please mind the connecting position of the male and female connectors, don't assemble the LCD in improper ways shown below.



10.5. Precautions for Soldering LCD Module LCD

	Manual Soldering	Machine Drag Soldering	Machine Press Soldering
Non-RoHS Product	290 ~350 Time: 3-5s	330 ~350 Speed: 15-17mm/s	300 ~330 Time: 3-6s. Press: 0.8~1.2Mpa
RoHS Product	340 ~370 Time: 3-5s	350 ~370 Speed: 15-17mm/s	330 ~360 Time: 3-6s Press: 0.8~1.2Mpa

- 1) If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation (This does not apply in the case of a non-halogen type of flux). It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage due to flux spatters.

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- 2) When soldering the LCD module and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.

LCD

- 3) When remove the LCD module from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.

LCD

10.6. Precautions for Operation

- 1) Viewing angle varies with the change of liquid crystal driving voltage (VLCD). Adjust VLCD to show the best contrast.

(VLCD) . VLCD

- 2) It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage than the limit will damage the driver IC. An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.

LCD

- 3) Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operating temperature.

- 4) If the display area is pushed hard, the display will cause pixel short, it will become the display defect.

- 5) A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit. Usage under the maximum operating temperature, 50%RH or less is required.

50%

LCD

- 6) Input logic voltage before apply analog high voltage such as LCD driving voltage when power on. Remove analog high voltage before logic voltage when power off the module. Input each signal after the positive/negative voltage becomes stable.

LCD

- 7) Please keep the temperature within the specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off may occur with high temperature and high humidity.

- 8) Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

- 9) If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

10.7. Safety

- 1) It is recommended to crush damaged or unnecessary LCD into pieces and wash them off with solvents such as acetone and ethanol, which should later be burned.
LCD
- 2) If any liquid leaks out of a damaged glass cell and comes in contact with the hands, wash off thoroughly with soap and water.

10.8. Limited Warranty

Unless agreed between SWI and the customer, SWI will replace or repair any of its LCD modules which are found to be functionally defective when inspected in accordance with SWI LCD acceptance standards for a period of one year from date of production. Cosmetic/visual defects must be returned to SWI within 90 days of shipment. Confirmation of such date shall be based on data code on product. The warranty liability of SWI limited to repair and/or replace on the terms set forth above. SWI will not be responsible for any subsequent or consequential events.

LCD / LCD
90 /

10.9. Return LCD Module under Warranty LCD

- 1) No warranty can be granted if the precautions stated above have been disregarded. The typical examples of violations are :

- Broken LCD glass.
LCD
- PCB eyelet is damaged or modified.
- PCB conductors damaged.
- Circuit modified in any way, including addition of components.
- PCB tampered with by grinding, engraving or painting varnish.
- Soldering to or modifying the bezel in any manner.

- 2) Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects. Any connectors or cable installed by the customer must be

removed completely without damaging the PCB eyelet, conductors and terminals.

11) PRIOR CONSULTING MATTERS

- 1) For SWI standard products, we keep the right to change the materials and processes without prior notification to our customers.
- 2) For OEM products, if any changes are needed which may affect the product property, we will consult with our customer in advance.
OEM
- 3) If you have special requirement about reliability condition, please let us know before you start the test on our samples.